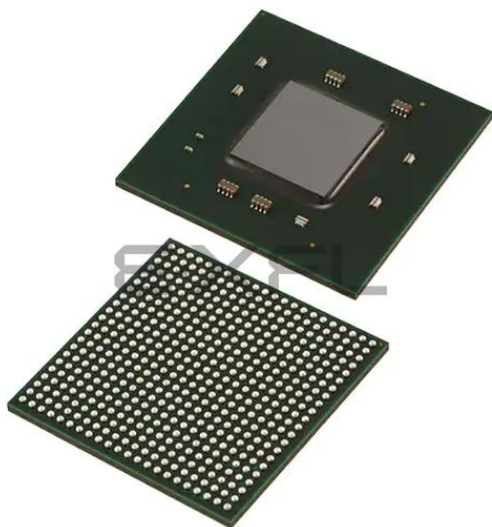




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	5125
Number of Logic Elements/Cells	65600
Total RAM Bits	4976640
Number of I/O	285
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	484-BBGA, FCBGA
Supplier Device Package	484-FCBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc7k70t-3fbg484e

Table 6: Typical Quiescent Supply Current (Cont'd)

Symbol	Description	Device	Speed Grade				Units
			1.0V			0.9V	
			-3	-2/-2L	-1	-2L	
I _{CCBRAMQ}	Quiescent V _{CCBRAM} supply current	XC7K70T	6	6	6	6	mA
		XC7K160T	14	14	14	14	mA
		XC7K325T	19	19	19	19	mA
		XC7K355T	31	31	31	31	mA
		XC7K410T	34	34	34	34	mA
		XC7K420T	41	41	41	41	mA
		XC7K480T	41	41	41	41	mA

Notes:

1. Typical values are specified at nominal voltage, 85°C junction temperatures (T_j) with single-ended SelectIO resources.
2. Typical values are for blank configured devices with no output current loads, no active input pull-up resistors, all I/O pins are 3-state and floating.
3. Use the XPower™ Estimator (XPE) spreadsheet tool (download at <http://www.xilinx.com/power>) to calculate static power consumption for conditions other than those specified.

Power-On/Off Power Supply Sequencing

The recommended power-on sequence is V_{CCINT}, V_{CCBRAM}, V_{CCAUX}, V_{CCAUX_IO}, and V_{CCO} to achieve minimum current draw and ensure that the I/Os are 3-stated at power-on. The recommended power-off sequence is the reverse of the power-on sequence. If V_{CCINT} and V_{CCBRAM} have the same recommended voltage levels then both can be powered by the same supply and ramped simultaneously. If V_{CCAUX}, V_{CCAUX_IO}, and V_{CCO} have the same recommended voltage levels then they can be powered by the same supply and ramped simultaneously.

For V_{CCO} voltages of 3.3V in HR I/O banks and configuration bank 0:

- The voltage difference between V_{CCO} and V_{CCAUX} must not exceed 2.625V for longer than T_{VCCO2VCCAUX} for each power-on/off cycle to maintain device reliability levels.
- The T_{VCCO2VCCAUX} time can be allocated in any percentage between the power-on and power-off ramps.

The recommended power-on sequence to achieve minimum current draw for the GTX transceivers is V_{CCINT}, V_{MGTAVCC}, V_{MGTAVTT} OR V_{MGTAVCC}, V_{CCINT}, V_{MGTAVTT}. There is no recommended sequencing for V_{MGTVCCAUX}. Both V_{MGTAVCC} and V_{CCINT} can be ramped simultaneously. The recommended power-off sequence is the reverse of the power-on sequence to achieve minimum current draw.

If these recommended sequences are not met, current drawn from V_{MGTAVTT} can be higher than specifications during power-up and power-down.

- When V_{MGTAVTT} is powered before V_{MGTAVCC} and V_{MGTAVTT} - V_{MGTAVCC} > 150 mV and V_{MGTAVCC} < 0.7V, the V_{MGTAVTT} current draw can increase by 460 mA per transceiver during V_{MGTAVCC} ramp up. The duration of the current draw can be up to 0.3 x T_{MGTAVCC} (ramp time from GND to 90% of V_{MGTAVCC}). The reverse is true for power-down.
- When V_{MGTAVTT} is powered before V_{CCINT} and V_{MGTAVTT} - V_{CCINT} > 150 mV and V_{CCINT} < 0.7V, the V_{MGTAVTT} current draw can increase by 50 mA per transceiver during V_{CCINT} ramp up. The duration of the current draw can be up to 0.3 x T_{VCCINT} (ramp time from GND to 90% of V_{CCINT}). The reverse is true for power-down.

LVDS DC Specifications (LVDS_25)

The LVDS_25 standard is available in the HR I/O banks. See [UG471: 7 Series FPGAs SelectIO Resources User Guide](#) for more information.

Table 12: LVDS_25 DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		2.375	2.500	2.625	V
V_{OH}	Output High Voltage for Q and $\overline{Q}$	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	–	–	1.675	V
V_{OL}	Output Low Voltage for Q and $\overline{Q}$	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	0.700	–	–	V
V_{ODIFF}	Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	247	350	600	mV
V_{OCM}	Output Common-Mode Voltage	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	1.000	1.250	1.425	V
V_{IDIFF}	Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High		100	350	600	mV
V_{ICM}	Input Common-Mode Voltage		0.300	1.200	1.425	V

LVDS DC Specifications (LVDS)

The LVDS standard is available in the HP I/O banks. See [UG471: 7 Series FPGAs SelectIO Resources User Guide](#) for more information.

Table 13: LVDS DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		1.710	1.800	1.890	V
V_{OH}	Output High Voltage for Q and $\overline{Q}$	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	–	–	1.675	V
V_{OL}	Output Low Voltage for Q and $\overline{Q}$	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	0.825	–	–	V
V_{ODIFF}	Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	247	350	600	mV
V_{OCM}	Output Common-Mode Voltage	$R_T = 100\ \Omega$ across Q and $\overline{Q}$ signals	1.000	1.250	1.425	V
V_{IDIFF}	Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	Common-mode input voltage = 1.25V	100	350	600	mV
V_{ICM}	Input Common-Mode Voltage	Differential input voltage = ± 350 mV	0.300	1.200	1.425	V

AC Switching Characteristics

All values represented in this data sheet are based on the speed specifications in ISE® software 14.3 v1.07 for the -3, -2, -2L(1.0V), -1, and v1.06 for -2L(0.9V) speed grades.

Switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance Product Specification

These specifications are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary Product Specification

These specifications are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Product Specification

These specifications are released once enough production silicon of a particular device family member has been characterized to provide full correlation between specifications and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to production before faster speed grades.

Testing of AC Switching Characteristics

Internal timing parameters are derived from measuring internal test patterns. All AC switching characteristics are representative of worst-case supply voltage and junction temperature conditions.

For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Kintex-7 FPGAs.

Speed Grade Designations

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device. [Table 14](#) correlates the current status of each Kintex-7 device on a per speed grade basis.

Table 14: Kintex-7 Device Speed Grade Designations

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XC7K70T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K160T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K325T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K355T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K410T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K420T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)
XC7K480T			-3, -2, -2L(1.0V), -1, and -2L (0.9V)

IOB Pad Input/Output/3-State

Table 19 (3.3V high-range IOB (HR)) and **Table 20** (1.8V high-performance IOB (HP)) summarizes the values of standard-specific data input delay adjustments, output delays terminating at pads (based on standard) and 3-state delays.

- T_{IOPI} is described as the delay from IOB pad through the input buffer to the I-pin of an IOB pad. The delay varies depending on the capability of the SelectIO input buffer.
- T_{IOOP} is described as the delay from the O pin to the IOB pad through the output buffer of an IOB pad. The delay varies depending on the capability of the SelectIO output buffer.
- T_{IOTP} is described as the delay from the T pin to the IOB pad through the output buffer of an IOB pad, when 3-state is disabled. The delay varies depending on the SelectIO capability of the output buffer. In HP I/O banks, the internal DCI termination turn-on time is always faster than T_{IOTP} when the DCITERMDISABLE pin is used. In HR I/O banks, the IN_TERM termination turn-on time is always faster than T_{IOTP} when the INTERMDISABLE pin is used.

Table 19: 3.3V IOB High Range (HR) Switching Characteristics

I/O Standard	T _{IOPI}				T _{IOOP}				T _{IOTP}				Units
	Speed Grade				Speed Grade				Speed Grade				
	1.0V			0.9V	1.0V			0.9V	1.0V			0.9V	
	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	
LVTTTL_S4	1.31	1.42	1.64	1.51	5.27	5.63	6.05	4.13	6.03	6.49	7.04	4.64	ns
LVTTTL_S8	1.31	1.42	1.64	1.51	4.45	4.83	5.30	3.86	5.21	5.69	6.29	4.38	ns
LVTTTL_S12	1.31	1.42	1.64	1.51	4.45	4.83	5.29	3.84	5.21	5.69	6.28	4.36	ns
LVTTTL_S16	1.31	1.42	1.64	1.51	3.47	3.88	4.40	3.39	4.23	4.74	5.39	3.91	ns
LVTTTL_S24	1.31	1.42	1.64	1.51	3.58	3.99	4.51	3.61	4.34	4.85	5.50	4.13	ns
LVTTTL_F4	1.31	1.42	1.64	1.51	4.70	4.98	5.29	3.58	5.46	5.84	6.28	4.09	ns
LVTTTL_F8	1.31	1.42	1.64	1.51	3.66	4.06	4.56	3.06	4.42	4.92	5.55	3.58	ns
LVTTTL_F12	1.31	1.42	1.64	1.51	3.66	4.06	4.56	3.05	4.42	4.92	5.55	3.56	ns
LVTTTL_F16	1.31	1.42	1.64	1.51	2.57	2.85	3.15	2.88	3.33	3.71	4.14	3.39	ns
LVTTTL_F24	1.31	1.42	1.64	1.51	2.41	2.64	2.89	2.94	3.17	3.50	3.88	3.45	ns
LVDS_25 ⁽¹⁾	0.64	0.68	0.80	0.83	1.36	1.47	1.55	1.58	2.12	2.33	2.54	2.09	ns
MINI_LVDS_25	0.68	0.70	0.79	0.83	1.36	1.47	1.55	1.59	2.12	2.33	2.54	2.11	ns
BLVDS_25 ⁽¹⁾	0.65	0.69	0.80	0.83	1.83	2.02	2.20	2.16	2.59	2.88	3.19	2.67	ns
RSDS_25 (point to point) ⁽¹⁾	0.63	0.68	0.79	0.83	1.36	1.48	1.55	1.59	2.12	2.34	2.54	2.11	ns
PPDS_25 ⁽¹⁾	0.65	0.69	0.80	0.83	1.36	1.49	1.58	1.59	2.12	2.35	2.57	2.11	ns
TMDS_33 ⁽¹⁾	0.72	0.76	0.86	0.83	1.43	1.54	1.60	1.70	2.19	2.40	2.59	2.22	ns
PCI33_3 ⁽¹⁾	1.28	1.41	1.65	1.50	2.71	3.08	3.52	3.42	3.47	3.94	4.51	3.94	ns
HSUL_12	0.63	0.64	0.71	0.79	2.06	2.31	2.59	2.13	2.82	3.17	3.58	2.64	ns
DIFF_HSUL_12	0.58	0.61	0.70	0.81	1.83	2.04	2.26	1.92	2.59	2.90	3.25	2.44	ns
HSTL_I_S	0.61	0.64	0.73	0.79	1.55	1.69	1.80	1.91	2.31	2.55	2.79	2.42	ns
HSTL_II_S	0.61	0.64	0.73	0.78	1.21	1.34	1.43	1.70	1.97	2.20	2.42	2.22	ns
HSTL_I_18_S	0.64	0.67	0.76	0.79	1.28	1.39	1.45	1.58	2.04	2.25	2.44	2.09	ns
HSTL_II_18_S	0.64	0.67	0.76	0.79	1.18	1.31	1.40	1.69	1.94	2.17	2.39	2.20	ns
DIFF_HSTL_I_S	0.63	0.67	0.77	0.78	1.42	1.54	1.61	1.84	2.18	2.40	2.60	2.36	ns
DIFF_HSTL_II_S	0.63	0.67	0.77	0.79	1.15	1.24	1.27	1.78	1.91	2.10	2.26	2.30	ns
DIFF_HSTL_I_18_S	0.65	0.69	0.78	0.79	1.27	1.38	1.43	1.67	2.03	2.24	2.42	2.19	ns
DIFF_HSTL_II_18_S	0.65	0.69	0.78	0.81	1.14	1.23	1.26	1.72	1.90	2.09	2.25	2.23	ns

Table 19: 3.3V IOB High Range (HR) Switching Characteristics (Cont'd)

I/O Standard	T _{IOPI}				T _{IOOP}				T _{IOTP}				Units
	Speed Grade				Speed Grade				Speed Grade				
	1.0V			0.9V	1.0V			0.9V	1.0V			0.9V	
	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	
HSTL_I_F	0.61	0.64	0.73	0.79	1.10	1.19	1.23	1.41	1.86	2.05	2.22	1.92	ns
HSTL_II_F	0.61	0.64	0.73	0.78	1.05	1.18	1.28	1.42	1.81	2.04	2.27	1.94	ns
HSTL_I_18_F	0.64	0.67	0.76	0.79	1.05	1.18	1.28	1.44	1.81	2.04	2.27	1.95	ns
HSTL_II_18_F	0.64	0.67	0.76	0.79	1.03	1.14	1.23	1.42	1.79	2.00	2.22	1.94	ns
DIFF_HSTL_I_F	0.63	0.67	0.77	0.78	1.09	1.18	1.22	1.48	1.85	2.04	2.21	2.00	ns
DIFF_HSTL_II_F	0.63	0.67	0.77	0.79	1.02	1.11	1.14	1.48	1.78	1.97	2.13	2.00	ns
DIFF_HSTL_I_18_F	0.65	0.69	0.78	0.79	1.08	1.17	1.21	1.48	1.84	2.03	2.20	2.00	ns
DIFF_HSTL_II_18_F	0.65	0.69	0.78	0.81	1.01	1.10	1.13	1.48	1.77	1.96	2.12	2.00	ns
LVC MOS33_S4	1.31	1.40	1.60	1.54	5.23	5.61	6.09	4.13	5.99	6.47	7.08	4.64	ns
LVC MOS33_S8	1.31	1.40	1.60	1.54	4.46	4.85	5.33	3.84	5.22	5.71	6.32	4.36	ns
LVC MOS33_S12	1.31	1.40	1.60	1.54	3.46	3.89	4.42	3.41	4.22	4.75	5.41	3.92	ns
LVC MOS33_S16	1.31	1.40	1.60	1.54	3.06	3.43	3.88	3.72	3.82	4.29	4.87	4.23	ns
LVC MOS33_F4	1.31	1.40	1.60	1.54	4.70	5.01	5.36	3.58	5.46	5.87	6.35	4.09	ns
LVC MOS33_F8	1.31	1.40	1.60	1.54	3.62	4.04	4.56	3.06	4.38	4.90	5.55	3.58	ns
LVC MOS33_F12	1.31	1.40	1.60	1.54	2.57	2.85	3.15	2.88	3.33	3.71	4.14	3.39	ns
LVC MOS33_F16	1.31	1.40	1.60	1.54	2.44	2.69	2.96	2.88	3.20	3.55	3.95	3.39	ns
LVC MOS25_S4	1.08	1.16	1.32	1.36	4.49	4.80	5.16	3.44	5.25	5.66	6.15	3.95	ns
LVC MOS25_S8	1.08	1.16	1.32	1.36	3.66	4.04	4.49	3.20	4.42	4.90	5.48	3.72	ns
LVC MOS25_S12	1.08	1.16	1.32	1.36	2.77	3.10	3.49	2.80	3.53	3.96	4.48	3.31	ns
LVC MOS25_S16	1.08	1.16	1.32	1.36	3.24	3.62	4.09	3.14	4.00	4.48	5.08	3.66	ns
LVC MOS25_F4	1.08	1.16	1.32	1.36	3.96	4.31	4.72	3.06	4.72	5.17	5.71	3.58	ns
LVC MOS25_F8	1.08	1.16	1.32	1.36	2.43	2.87	3.42	2.50	3.19	3.73	4.41	3.02	ns
LVC MOS25_F12	1.08	1.16	1.32	1.36	2.23	2.63	3.13	2.48	2.99	3.49	4.12	3.00	ns
LVC MOS25_F16	1.08	1.16	1.32	1.36	1.92	2.17	2.45	2.33	2.68	3.03	3.44	2.84	ns
LVC MOS18_S4	0.64	0.66	0.74	0.87	3.24	3.45	3.66	1.91	4.00	4.31	4.65	2.42	ns
LVC MOS18_S8	0.64	0.66	0.74	0.87	2.58	2.91	3.31	2.50	3.34	3.77	4.30	3.02	ns
LVC MOS18_S12	0.64	0.66	0.74	0.87	2.58	2.91	3.31	2.50	3.34	3.77	4.30	3.02	ns
LVC MOS18_S16	0.64	0.66	0.74	0.87	1.82	2.03	2.24	1.84	2.58	2.89	3.23	2.36	ns
LVC MOS18_S24 ⁽¹⁾	0.64	0.66	0.74	0.87	1.74	1.92	2.08	1.92	2.50	2.78	3.07	2.44	ns
LVC MOS18_F4	0.64	0.66	0.74	0.87	3.12	3.31	3.49	1.77	3.88	4.17	4.48	2.28	ns
LVC MOS18_F8	0.64	0.66	0.74	0.87	1.91	2.13	2.36	2.00	2.67	2.99	3.35	2.52	ns
LVC MOS18_F12	0.64	0.66	0.74	0.87	1.91	2.13	2.36	2.00	2.67	2.99	3.35	2.52	ns
LVC MOS18_F16	0.64	0.66	0.74	0.87	1.52	1.68	1.81	1.72	2.28	2.54	2.80	2.23	ns
LVC MOS18_F24 ⁽¹⁾	0.64	0.66	0.74	0.87	1.34	1.46	1.55	1.66	2.10	2.32	2.54	2.17	ns
LVC MOS15_S4	0.66	0.69	0.81	0.90	3.48	3.74	4.03	2.22	4.24	4.60	5.02	2.73	ns
LVC MOS15_S8	0.66	0.69	0.81	0.90	2.37	2.67	3.01	2.41	3.13	3.53	4.00	2.92	ns
LVC MOS15_S12	0.66	0.69	0.81	0.90	1.83	2.03	2.23	1.91	2.59	2.89	3.22	2.42	ns

Table 20: 1.8V IOB High Performance (HP) Switching Characteristics

I/O Standard	T _{IOPI}				T _{IOOP}				T _{IOTP}				Units
	Speed Grade				Speed Grade				Speed Grade				
	1.0V			0.9V	1.0V			0.9V	1.0V			0.9V	
	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	-3	-2/-2L	-1	-2L	
LVDS	0.75	0.79	0.92	0.89	1.05	1.17	1.24	1.43	1.68	1.92	2.06	2.04	ns
HSUL_12	0.69	0.72	0.82	0.95	1.65	1.84	2.05	1.80	2.29	2.59	2.87	2.41	ns
DIFF_HSUL_12	0.69	0.72	0.82	0.92	1.65	1.84	2.05	1.47	2.29	2.59	2.87	2.08	ns
HSTL_I_S	0.68	0.72	0.82	0.84	1.15	1.28	1.38	1.46	1.79	2.03	2.20	2.07	ns
HSTL_II_S	0.68	0.72	0.82	0.84	1.05	1.17	1.26	1.44	1.69	1.93	2.08	2.05	ns
HSTL_I_18_S	0.70	0.72	0.82	0.86	1.12	1.24	1.34	1.41	1.75	2.00	2.16	2.02	ns
HSTL_II_18_S	0.70	0.72	0.82	0.86	1.06	1.18	1.26	1.44	1.70	1.94	2.08	2.05	ns
HSTL_I_12_S	0.68	0.72	0.82	0.94	1.14	1.27	1.37	1.43	1.78	2.02	2.20	2.04	ns
HSTL_I_DCI_S	0.68	0.72	0.82	0.78	1.11	1.23	1.33	1.36	1.74	1.99	2.15	1.98	ns
HSTL_II_DCI_S	0.68	0.72	0.82	0.78	1.05	1.17	1.26	1.33	1.69	1.93	2.08	1.94	ns
HSTL_II_T_DCI_S	0.70	0.72	0.82	0.76	1.15	1.28	1.38	1.40	1.78	2.03	2.20	2.01	ns
HSTL_I_DCI_18_S	0.70	0.72	0.82	0.76	1.11	1.23	1.33	1.36	1.74	1.99	2.15	1.98	ns
HSTL_II_DCI_18_S	0.70	0.72	0.82	0.76	1.05	1.16	1.24	1.32	1.69	1.92	2.06	1.93	ns
HSTL_II_T_DCI_18_S	0.70	0.72	0.82	0.76	1.11	1.23	1.33	1.36	1.74	1.99	2.15	1.98	ns
DIFF_HSTL_I_S	0.75	0.79	0.92	0.89	1.15	1.28	1.38	1.47	1.79	2.03	2.20	2.08	ns
DIFF_HSTL_II_S	0.75	0.79	0.92	0.89	1.05	1.17	1.26	1.47	1.69	1.93	2.08	2.08	ns
DIFF_HSTL_I_DCI_S	0.75	0.79	0.92	0.76	1.15	1.28	1.38	1.47	1.78	2.03	2.20	2.08	ns
DIFF_HSTL_II_DCI_S	0.75	0.79	0.92	0.76	1.05	1.17	1.26	1.40	1.69	1.93	2.08	2.01	ns
DIFF_HSTL_I_18_S	0.75	0.79	0.92	0.89	1.12	1.24	1.34	1.46	1.75	2.00	2.16	2.07	ns
DIFF_HSTL_II_18_S	0.75	0.79	0.92	0.89	1.06	1.18	1.26	1.47	1.70	1.94	2.08	2.08	ns
DIFF_HSTL_I_DCI_18_S	0.75	0.79	0.92	0.75	1.11	1.23	1.33	1.46	1.74	1.99	2.15	2.07	ns
DIFF_HSTL_II_DCI_18_S	0.75	0.79	0.92	0.75	1.05	1.16	1.24	1.41	1.69	1.92	2.06	2.02	ns
DIFF_HSTL_II_T_DCI_18_S	0.75	0.79	0.92	0.76	1.11	1.23	1.33	1.46	1.74	1.99	2.15	2.07	ns
HSTL_I_F	0.68	0.72	0.82	0.84	1.02	1.14	1.22	1.26	1.66	1.90	2.04	1.87	ns
HSTL_II_F	0.68	0.72	0.82	0.84	0.97	1.08	1.15	1.29	1.61	1.84	1.97	1.90	ns
HSTL_I_18_F	0.70	0.72	0.82	0.86	1.04	1.16	1.24	1.32	1.68	1.91	2.06	1.93	ns
HSTL_II_18_F	0.70	0.72	0.82	0.86	0.98	1.09	1.16	1.35	1.62	1.85	1.98	1.96	ns
HSTL_I_12_F	0.68	0.72	0.82	0.94	1.02	1.13	1.21	1.26	1.65	1.88	2.03	1.87	ns
HSTL_I_DCI_F	0.68	0.72	0.82	0.78	1.04	1.16	1.24	1.30	1.67	1.91	2.06	1.91	ns
HSTL_II_DCI_F	0.68	0.72	0.82	0.78	0.97	1.08	1.15	1.22	1.61	1.84	1.97	1.83	ns
HSTL_II_T_DCI_F	0.70	0.72	0.82	0.76	1.02	1.14	1.22	1.26	1.66	1.90	2.04	1.87	ns
HSTL_I_DCI_18_F	0.70	0.72	0.82	0.76	1.04	1.16	1.24	1.30	1.67	1.91	2.06	1.91	ns
HSTL_II_DCI_18_F	0.70	0.72	0.82	0.76	0.98	1.09	1.16	1.27	1.61	1.85	1.98	1.88	ns
HSTL_II_T_DCI_18_F	0.70	0.72	0.82	0.76	1.04	1.16	1.24	1.30	1.67	1.91	2.06	1.91	ns
DIFF_HSTL_I_F	0.75	0.79	0.92	0.89	1.02	1.14	1.22	1.35	1.66	1.90	2.04	1.96	ns
DIFF_HSTL_II_F	0.75	0.79	0.92	0.89	0.97	1.08	1.15	1.35	1.61	1.84	1.97	1.96	ns
DIFF_HSTL_I_DCI_F	0.75	0.79	0.92	0.76	1.02	1.14	1.22	1.35	1.66	1.90	2.04	1.96	ns

Input/Output Logic Switching Characteristics

Table 22: ILOGIC Switching Characteristics

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Setup/Hold						
T _{ICE1CK} /T _{ICKCE1}	CE1 pin Setup/Hold with respect to CLK	0.42/0.00	0.48/0.00	0.67/0.00	0.56/−0.16	ns
T _{ISRCK} /T _{ICKSR}	SR pin Setup/Hold with respect to CLK	0.53/0.01	0.61/0.01	0.99/0.01	0.88/−0.30	ns
T _{IDOCKE2} /T _{IOCKDE2}	D pin Setup/Hold with respect to CLK without Delay (HP I/O banks only)	0.01/0.27	0.01/0.29	0.01/0.34	0.01/0.41	ns
T _{IDOCKDE2} /T _{IOCKDDE2}	DDLY pin Setup/Hold with respect to CLK (using IDELAY) (HP I/O banks only)	0.01/0.27	0.02/0.29	0.02/0.34	0.01/0.41	ns
T _{IDOCKE3} /T _{IOCKDE3}	D pin Setup/Hold with respect to CLK without Delay (HR I/O banks only)	0.01/0.27	0.01/0.29	0.01/0.34	0.01/0.41	ns
T _{IDOCKDE3} /T _{IOCKDDE3}	DDLY pin Setup/Hold with respect to CLK (using IDELAY) (HR I/O banks only)	0.01/0.27	0.02/0.29	0.02/0.34	0.01/0.41	ns
Combinatorial						
T _{IDIE2}	D pin to O pin propagation delay, no Delay (HP I/O banks only)	0.09	0.10	0.12	0.14	ns
T _{IDIDE2}	DDLY pin to O pin propagation delay (using IDELAY) (HP I/O banks only)	0.10	0.11	0.13	0.15	ns
T _{IDIE3}	D pin to O pin propagation delay, no Delay (HR I/O banks only)	0.09	0.10	0.12	0.14	ns
T _{IDIDE3}	DDLY pin to O pin propagation delay (using IDELAY) (HR I/O banks only)	0.10	0.11	0.13	0.15	ns
Sequential Delays						
T _{IDLOE2}	D pin to Q1 pin using flip-flop as a latch without Delay (HP I/O banks only)	0.36	0.39	0.45	0.54	ns
T _{IDLODE2}	DDLY pin to Q1 pin using flip-flop as a latch (using IDELAY) (HP I/O banks only)	0.36	0.39	0.45	0.55	ns
T _{IDLOE3}	D pin to Q1 pin using flip-flop as a latch without Delay (HR I/O banks only)	0.36	0.39	0.45	0.54	ns
T _{IDLODE3}	DDLY pin to Q1 pin using flip-flop as a latch (using IDELAY) (HR I/O banks only)	0.36	0.39	0.45	0.55	ns
T _{ICKQ}	CLK to Q outputs	0.47	0.50	0.58	0.71	ns
T _{RQ_ILOGICE2}	SR pin to OQ/TQ out (HP I/O banks only)	0.84	0.94	1.16	1.32	ns
T _{GSRQ_ILOGICE2}	Global Set/Reset to Q outputs (HP I/O banks only)	7.60	7.60	10.51	11.39	ns
T _{RQ_ILOGICE3}	SR pin to OQ/TQ out (HR I/O banks only)	0.84	0.94	1.16	1.32	ns
T _{GSRQ_ILOGICE3}	Global Set/Reset to Q outputs (HR I/O banks only)	7.60	7.60	10.51	11.39	ns
Set/Reset						
T _{RPW_ILOGICE2}	Minimum Pulse Width, SR inputs (HP I/O banks only)	0.54	0.63	0.63	0.68	ns, Min
T _{RPW_ILOGICE3}	Minimum Pulse Width, SR inputs (HR I/O banks only)	0.54	0.63	0.63	0.68	ns, Min

Table 23: OLOGIC Switching Characteristics

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Setup/Hold						
T _{ODCK} /T _{OCKD}	D1/D2 pins Setup/Hold with respect to CLK	0.45/−0.13	0.50/−0.13	0.58/−0.13	0.79/−0.18	ns
T _{OOCECK} /T _{OCKOCE}	OCE pin Setup/Hold with respect to CLK	0.28/0.03	0.29/0.03	0.45/0.03	0.35/−0.10	ns
T _{OSRCK} /T _{OCKSR}	SR pin Setup/Hold with respect to CLK	0.32/0.18	0.38/0.18	0.70/0.18	0.62/−0.04	ns
T _{OTCK} /T _{OCKT}	T1/T2 pins Setup/Hold with respect to CLK	0.49/−0.16	0.56/−0.16	0.68/−0.16	0.67/−0.18	ns
T _{OTCECK} /T _{OCKTCE}	TCE pin Setup/Hold with respect to CLK	0.28/0.01	0.30/0.01	0.45/0.01	0.31/−0.10	ns
Combinatorial						
T _{ODQ}	D1 to OQ out or T1 to TQ out	0.73	0.81	0.97	1.18	ns
Sequential Delays						
T _{OCKQ}	CLK to OQ/TQ out	0.41	0.43	0.49	0.63	ns
T _{RQ_OLOGICE2}	SR pin to OQ/TQ out (HP I/O banks only)	0.63	0.70	0.83	1.12	ns
T _{GSRQ_OLOGICE2}	Global Set/Reset to Q outputs (HP I/O banks only)	7.60	7.60	10.51	11.39	ns
T _{RQ_OLOGICE3}	SR pin to OQ/TQ out (HR I/O banks only)	0.63	0.70	0.83	1.12	ns
T _{GSRQ_OLOGICE3}	Global Set/Reset to Q outputs (HR I/O banks only)	7.60	7.60	10.51	11.39	ns
Set/Reset						
T _{RPW_OLOGICE2}	Minimum Pulse Width, SR inputs (HP I/O banks only)	0.54	0.54	0.63	0.68	ns, Min
T _{RPW_OLOGICE3}	Minimum Pulse Width, SR inputs (HR I/O banks only)	0.54	0.54	0.63	0.68	ns, Min

Input Serializer/Deserializer Switching Characteristics

Table 24: ISERDES Switching Characteristics

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Setup/Hold for Control Lines						
T _{ISCK_BITSLIP} / T _{ISCKC_BITSLIP}	BITSLIP pin Setup/Hold with respect to CLKDIV	0.01/0.12	0.02/0.13	0.02/0.15	0.02/0.21	ns
T _{ISCK_C} / T _{ISCKC_C} ⁽²⁾	CE pin Setup/Hold with respect to CLK (for CE1)	0.39/−0.02	0.44/−0.02	0.63/−0.02	0.51/−0.22	ns
T _{ISCK_C} / T _{ISCKC_C} ⁽²⁾	CE pin Setup/Hold with respect to CLKDIV (for CE2)	−0.12/0.29	−0.12/0.31	−0.12/0.35	−0.17/0.40	ns
Setup/Hold for Data Lines						
T _{ISDCK_D} /T _{ISCKD_D}	D pin Setup/Hold with respect to CLK	−0.02/0.11	−0.02/0.12	−0.02/0.15	−0.04/0.19	ns
T _{ISDCK_DDL} / T _{ISCKD_DDL}	DDL pin Setup/Hold with respect to CLK (using IDELAY) ⁽¹⁾	−0.02/0.11	−0.02/0.12	−0.02/0.15	−0.03/0.19	ns
T _{ISDCK_D_DDR} / T _{ISCKD_D_DDR}	D pin Setup/Hold with respect to CLK at DDR mode	−0.02/0.11	−0.02/0.12	−0.02/0.15	−0.04/0.19	ns
T _{ISDCK_DDL_DDR} / T _{ISCKD_DDL_DDR}	D pin Setup/Hold with respect to CLK at DDR mode (using IDELAY) ⁽¹⁾	0.11/0.11	0.12/0.12	0.15/0.15	0.19/0.19	ns
Sequential Delays						
T _{ISCKO_Q}	CLKDIV to out at Q pin	0.46	0.47	0.58	0.67	ns
Propagation Delays						
T _{ISDO_DO}	D input to DO output pin	0.09	0.10	0.12	0.14	ns

Notes:

1. Recorded at 0 tap value.
2. T_{ISCK_CE2} and T_{ISCK_CE2} are reported as T_{ISCK_CE}/T_{ISCK_CE} in TRACE report.

CLB Distributed RAM Switching Characteristics (SLICEM Only)

Table 29: CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Sequential Delays						
T _{SHCKO}	Clock to A – B outputs	0.68	0.70	0.85	1.08	ns, Max
T _{SHCKO_1}	Clock to AMUX – BMUX outputs	0.91	0.95	1.15	1.44	ns, Max
Setup and Hold Times Before/After Clock CLK						
T _{DS_LRAM} /T _{DH_LRAM}	A – D inputs to CLK	0.45/0.23	0.45/0.24	0.54/0.27	0.69/0.33	ns, Min
T _{AS_LRAM} /T _{AH_LRAM}	Address An inputs to clock	0.13/0.50	0.14/0.50	0.17/0.58	0.21/0.63	ns, Min
	Address An inputs through MUXs and/or carry logic to clock	0.40/0.16	0.42/0.17	0.52/0.23	0.63/0.23	ns, Min
T _{WS_LRAM} /T _{WH_LRAM}	WE input to clock	0.29/0.09	0.30/0.09	0.36/0.09	0.46/0.10	ns, Min
T _{CECK_LRAM} / T _{CKCE_LRAM}	CE input to CLK	0.29/0.09	0.30/0.09	0.37/0.09	0.47/0.10	ns, Min
Clock CLK						
T _{MPW}	Minimum pulse width	0.68	0.77	0.91	1.11	ns, Min
T _{MCP}	Minimum clock period	1.35	1.54	1.82	2.22	ns, Min

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time.
2. T_{SHCKO} also represents the CLK to XMUX output. Refer to TRACE report for the CLK to XMUX path.

CLB Shift Register Switching Characteristics (SLICEM Only)

Table 30: CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Sequential Delays						
T _{REG}	Clock to A – D outputs	0.96	0.98	1.20	1.35	ns, Max
T _{REG_MUX}	Clock to AMUX – DMUX output	1.19	1.23	1.50	1.72	ns, Max
T _{REG_M31}	Clock to DMUX output via M31 output	0.89	0.91	1.10	1.25	ns, Max
Setup and Hold Times Before/After Clock CLK						
T _{WS_SHFREG} / T _{WH_SHFREG}	WE input	0.26/0.09	0.27/0.09	0.33/0.09	0.41/0.10	ns, Min
T _{CECK_SHFREG} / T _{CKCE_SHFREG}	CE input to CLK	0.27/0.09	0.28/0.09	0.33/0.09	0.42/0.10	ns, Min
T _{DS_SHFREG} / T _{DH_SHFREG}	A – D inputs to CLK	0.28/0.26	0.28/0.26	0.33/0.30	0.41/0.36	ns, Min
Clock CLK						
T _{MPW_SHFREG}	Minimum pulse width	0.55	0.65	0.78	0.91	ns, Min

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time.

Table 31: Block RAM and FIFO Switching Characteristics (Cont'd)

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
$T_{RCKK_RSTRAM}/T_{RCKC_RSTRAM}$	Synchronous RSTRAM input	0.27/0.35	0.29/0.37	0.31/0.39	0.34/0.40	ns, Min
$T_{RCKK_WEA}/T_{RCKC_WEA}$	Write Enable (WE) input (Block RAM only)	0.38/0.15	0.41/0.16	0.46/0.17	0.54/0.19	ns, Min
$T_{RCKK_WREN}/T_{RCKC_WREN}$	WREN FIFO inputs	0.39/0.25	0.39/0.30	0.40/0.37	0.65/0.37	ns, Min
$T_{RCKK_RDEN}/T_{RCKC_RDEN}$	RDEN FIFO inputs	0.36/0.26	0.36/0.30	0.37/0.37	0.60/0.38	ns, Min
Reset Delays						
T_{RCO_FLAGS}	Reset RST to FIFO flags/pointers ⁽¹⁰⁾	0.76	0.83	0.93	1.06	ns, Max
$T_{RREC_RST}/T_{RREM_RST}$	FIFO reset recovery and removal timing ⁽¹¹⁾	1.59/–0.68	1.76/–0.68	2.01/–0.68	2.07/–0.60	ns, Max
Maximum Frequency						
$F_{MAX_BRAM_WF_NC}$	Block RAM (Write first and No change modes) When not in SDP RF mode	601.32	543.77	458.09	372.44	MHz
$F_{MAX_BRAM_RF_PERFORMANCE}$	Block RAM (Read first, Performance mode) When in SDP RF mode but no address overlap between port A and port B	601.32	543.77	458.09	372.44	MHz
$F_{MAX_BRAM_RF_DELAYED_WRITE}$	Block RAM (Read first, Delayed_write mode) When in SDP RF mode and there is possibility of overlap between port A and port B addresses	528.26	477.33	400.80	317.36	MHz
$F_{MAX_CAS_WF_NC}$	Block RAM Cascade (Write first, No change mode) When cascade but not in RF mode	551.27	493.83	408.00	322.48	MHz
$F_{MAX_CAS_RF_PERFORMANCE}$	Block RAM Cascade (Read first, Performance mode) When in cascade with RF mode and no possibility of address overlap/one port is disabled	551.27	493.83	408.00	322.48	MHz
$F_{MAX_CAS_RF_DELAYED_WRITE}$	When in cascade RF mode and there is a possibility of address overlap between port A and port B	478.27	427.35	350.88	267.38	MHz
F_{MAX_FIFO}	FIFO in all modes without ECC	601.32	543.77	458.09	372.44	MHz
F_{MAX_ECC}	Block RAM and FIFO in ECC configuration	484.26	430.85	351.12	254.13	MHz

Notes:

- TRACE will report all of these parameters as T_{RCKO_DO} .
- T_{RCKO_DOR} includes T_{RCKO_DOW} , T_{RCKO_DOPR} , and T_{RCKO_DOPW} as well as the B port equivalent timing parameters.
- These parameters also apply to synchronous FIFO with $DO_REG = 0$.
- T_{RCKO_DO} includes T_{RCKO_DOP} as well as the B port equivalent timing parameters.
- These parameters also apply to multirate (asynchronous) and synchronous FIFO with $DO_REG = 1$.
- T_{RCKO_FLAGS} includes the following parameters: T_{RCKO_AEMPTY} , T_{RCKO_AFULL} , T_{RCKO_EMPTY} , T_{RCKO_FULL} , T_{RCKO_RDERR} , T_{RCKO_WRERR} .
- $T_{RCKO_POINTERS}$ includes both $T_{RCKO_RDCOUNT}$ and $T_{RCKO_WRCOUNT}$.
- The ADDR setup and hold must be met when EN is asserted (even when WE is deasserted). Otherwise, block RAM data corruption is possible.
- These parameters include both A and B inputs as well as the parity inputs of A and B.
- T_{RCO_FLAGS} includes the following flags: AEMPTY, AFULL, EMPTY, FULL, RDERR, WRERR, RDCOUNT, and WRCOUNT.
- RDEN and WREN must be held Low prior to and during reset. The FIFO reset must be asserted for at least five positive clock edges of the slowest clock (WRCLK or RDCLK).

Table 32: DSP48E1 Switching Characteristics (Cont'd)

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
Clock to Outs from Pipeline Register Clock to Output Pins						
T_DSPCKO_P_MREG	CLK MREG to P output	1.42	1.64	1.96	2.31	ns
T_DSPCKO_CARRYCASCOUT_MREG	CLK MREG to CARRYCASCOUT output	1.63	1.87	2.24	2.65	ns
T_DSPCKO_P_ADREG_MULT	CLK ADREG to P output using multiplier	2.30	2.63	3.13	3.90	ns
T_DSPCKO_CARRYCASCOUT_ADREG_MULT	CLK ADREG to CARRYCASCOUT output using multiplier	2.51	2.87	3.41	4.23	ns
Clock to Outs from Input Register Clock to Output Pins						
T_DSPCKO_P_AREG_MULT	CLK AREG to P output using multiplier	3.34	3.83	4.55	5.80	ns
T_DSPCKO_P_BREG	CLK BREG to P output not using multiplier	1.39	1.59	1.88	2.24	ns
T_DSPCKO_P_CREG	CLK CREG to P output not using multiplier	1.43	1.64	1.95	2.32	ns
T_DSPCKO_P_DREG_MULT	CLK DREG to P output using multiplier	3.32	3.80	4.51	5.74	ns
Clock to Outs from Input Register Clock to Cascading Output Pins						
T_DSPCKO_{ACOUT; BCOUT}_{AREG; BREG}	CLK (ACOUT, BCOUT) to {A,B} register output	0.55	0.62	0.74	0.87	ns
T_DSPCKO_CARRYCASCOUT_{AREG, BREG}_MULT	CLK (AREG, BREG) to CARRYCASCOUT output using multiplier	3.55	4.06	4.84	6.13	ns
T_DSPCKO_CARRYCASCOUT_BREG	CLK BREG to CARRYCASCOUT output not using multiplier	1.60	1.82	2.16	2.58	ns
T_DSPCKO_CARRYCASCOUT_DREG_MULT	CLK DREG to CARRYCASCOUT output using multiplier	3.52	4.03	4.79	6.07	ns
T_DSPCKO_CARRYCASCOUT_CREG	CLK CREG to CARRYCASCOUT output	1.64	1.88	2.23	2.65	ns
Maximum Frequency						
F_MAX	With all registers used	741.84	650.20	547.95	429.37	MHz
F_MAX_PATDET	With pattern detector	627.35	549.75	463.61	365.90	MHz
F_MAX_MULT_NOMREG	Two register multiply without MREG	412.20	360.75	303.77	248.32	MHz
F_MAX_MULT_NOMREG_PATDET	Two register multiply without MREG with pattern detect	374.25	327.65	276.01	225.73	MHz
F_MAX_PREADD_MULT_NOADREG	Without ADREG	468.82	408.66	342.70	263.44	MHz
F_MAX_PREADD_MULT_NOADREG_PATDET	Without ADREG with pattern detect	468.82	408.66	342.70	263.44	MHz
F_MAX_NOPIPELINEREG	Without pipeline registers (MREG, ADREG)	306.84	267.81	225.02	177.15	MHz
F_MAX_NOPIPELINEREG_PATDET	Without pipeline registers (MREG, ADREG) with pattern detect	285.23	249.13	209.38	165.32	MHz

MMCM Switching Characteristics

Table 38: MMCM Specification

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
MMCM_F _{INMAX}	Maximum Input Clock Frequency	1066.00	933.00	800.00	800.00	MHz
MMCM_F _{INMIN}	Minimum Input Clock Frequency	10.00	10.00	10.00	10.00	MHz
MMCM_F _{INJITTER}	Maximum Input Clock Period Jitter	< 20% of clock input period or 1 ns Max				
MMCM_F _{INDUTY}	Allowable Input Duty Cycle: 10—49 MHz	25.00	25.00	25.00	25.00	%
	Allowable Input Duty Cycle: 50—199 MHz	30.00	30.00	30.00	30.00	%
	Allowable Input Duty Cycle: 200—399 MHz	35.00	35.00	35.00	35.00	%
	Allowable Input Duty Cycle: 400—499 MHz	40.00	40.00	40.00	40.00	%
	Allowable Input Duty Cycle: >500 MHz	45.00	45.00	45.00	45.00	%
MMCM_F _{MIN_PSCLK}	Minimum Dynamic Phase Shift Clock Frequency	0.01	0.01	0.01	0.01	MHz
MMCM_F _{MAX_PSCLK}	Maximum Dynamic Phase Shift Clock Frequency	550.00	500.00	450.00	450.00	MHz
MMCM_F _{VCOMIN}	Minimum MMCM VCO Frequency	600.00	600.00	600.00	600.00	MHz
MMCM_F _{VCOMAX}	Maximum MMCM VCO Frequency	1600.00	1440.00	1200.00	1200.00	MHz
MMCM_F _{BANDWIDTH}	Low MMCM Bandwidth at Typical ⁽¹⁾	1.00	1.00	1.00	1.00	MHz
	High MMCM Bandwidth at Typical ⁽¹⁾	4.00	4.00	4.00	4.00	MHz
MMCM_T _{STATPHAOFFSET}	Static Phase Offset of the MMCM Outputs ⁽²⁾	0.12	0.12	0.12	0.12	ns
MMCM_T _{OUTJITTER}	MMCM Output Jitter	Note 3				
MMCM_T _{OUTDUTY}	MMCM Output Clock Duty Cycle Precision ⁽⁴⁾	0.20	0.20	0.20	0.25	ns
MMCM_T _{LOCKMAX}	MMCM Maximum Lock Time	100.00	100.00	100.00	100.00	μs
MMCM_F _{OUTMAX}	MMCM Maximum Output Frequency	1066.00	933.00	800.00	800.00	MHz
MMCM_F _{OUTMIN}	MMCM Minimum Output Frequency ⁽⁵⁾⁽⁶⁾	4.69	4.69	4.69	4.69	MHz
MMCM_T _{EXTFDVAR}	External Clock Feedback Variation	< 20% of clock input period or 1 ns Max				
MMCM_RST _{MINPULSE}	Minimum Reset Pulse Width	5.00	5.00	5.00	5.00	ns
MMCM_F _{PFDMAX}	Maximum Frequency at the Phase Frequency Detector with Bandwidth Set to High or Optimized	550.00	500.00	450.00	450.00	MHz
	Maximum Frequency at the Phase Frequency Detector with Bandwidth Set to Low	300.00	300.00	300.00	300.00	MHz
MMCM_F _{PFDMIN}	Minimum Frequency at the Phase Frequency Detector	10.00	10.00	10.00	10.00	MHz
MMCM_T _{FBDELAY}	Maximum Delay in the Feedback Path	3 ns Max or one CLKIN cycle				
MMCM Switching Characteristics Setup and Hold						
T _{MMCMDCK_PSEN} / T _{MMCMCKD_PSEN}	Setup and Hold of Phase Shift Enable	1.04/0.00	1.04/0.00	1.04/0.00	1.04/0.00	ns
T _{MMCMDCK_PSINCDEC} / T _{MMCMCKD_PSINCDEC}	Setup and Hold of Phase Shift Increment/Decrement	1.04/0.00	1.04/0.00	1.04/0.00	1.04/0.00	ns
T _{MMCMCKO_PSDONE}	Phase Shift Clock-to-Out of PSDONE	0.59	0.68	0.81	0.78	ns
Dynamic Reconfiguration Port (DRP) for MMCM Before and After DCLK						
T _{MMCMDCK_DADDR} / T _{MMCMCKD_DADDR}	DADDR Setup/Hold	1.25/0.15	1.40/0.15	1.63/0.15	1.43/0.00	ns, Min
T _{MMCMDCK_DI} / T _{MMCMCKD_DI}	DI Setup/Hold	1.25/0.15	1.40/0.15	1.63/0.15	1.43/0.00	ns, Min

Table 39: PLL Specification (Cont'd)

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
PLL_F _{PFDMAX}	Maximum Frequency at the Phase Frequency Detector with Bandwidth Set to High or Optimized	550.00	500.00	450.00	450.00	MHz
	Maximum Frequency at the Phase Frequency Detector with Bandwidth Set to Low	300.00	300.00	300.00	300.00	MHz
PLL_F _{PFDMIN}	Minimum Frequency at the Phase Frequency Detector	19.00	19.00	19.00	19.00	MHz
PLL_T _{FBDELAY}	Maximum Delay in the Feedback Path	3 ns Max or one CLKIN cycle				
Dynamic Reconfiguration Port (DRP) for PLL Before and After DCLK						
T _{PLLCKC_DADDR} / T _{PLLCKC_DADDR}	Setup and hold of D address	1.25/0.15	1.40/0.15	1.63/0.15	1.43/0.00	ns, Min
T _{PLLCKC_DI} / T _{PLLCKC_DI}	Setup and hold of D input	1.25/0.15	1.40/0.15	1.63/0.15	1.43/0.00	ns, Min
T _{PLLCKC_DEN} / T _{PLLCKC_DEN}	Setup and hold of D enable	1.76/0.00	1.97/0.00	2.29/0.00	2.40/0.00	ns, Min
T _{PLLCKC_DWE} / T _{PLLCKC_DWE}	Setup and hold of D write enable	1.25/0.15	1.40/0.15	1.63/0.15	1.43/0.00	ns, Min
T _{PLLCKO_DRDY}	CLK to out of DRDY	0.65	0.72	0.99	0.70	ns, Max
F _{DCK}	DCLK frequency	200.00	200.00	200.00	100.00	MHz, Max

Notes:

1. The PLL does not filter typical spread-spectrum input clocks because they are usually far below the bandwidth filter frequencies.
2. The static offset is measured between any PLL outputs with identical phase.
3. Values for this parameter are available in the Clocking Wizard.
See http://www.xilinx.com/products/intellectual-property/clocking_wizard.htm.
4. Includes global clock buffer.
5. Calculated as $F_{VCO}/128$ assuming output duty cycle is 50%.

Device Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Values are expressed in nanoseconds unless otherwise noted.

Table 45: Global Clock Input Setup and Hold Without MMCM/PLL with ZHOLD_DELAY on HR I/O Banks

Symbol	Description	Device	Speed Grade				Units
			1.0V			0.9V	
			-3	-2/-2L	-1	-2L	
Input Setup and Hold Time Relative to Global Clock Input Signal for SSTL15 Standard. ⁽¹⁾							
T _{PSFD} / T _{PHFD}	Full Delay (Legacy Delay or Default Delay) Global Clock Input and IFF ⁽²⁾ without MMCM/PLL with ZHOLD_DELAY on HR I/O Banks	XC7K70T	2.83/−0.29	2.95/−0.29	3.15/−0.29	4.96/−0.33	ns
		XC7K160T	3.17/−0.35	3.29/−0.35	3.55/−0.35	5.54/−0.49	ns
		XC7K325T	2.83/−0.06	2.94/−0.06	3.15/−0.06	5.18/−0.14	ns
		XC7K355T	3.26/−0.32	3.41/−0.32	3.67/−0.32	5.84/−0.49	ns
		XC7K410T	3.43/−0.34	3.59/−0.34	3.88/−0.34	6.21/−0.54	ns
		XC7K420T	3.37/−0.27	3.48/−0.27	3.76/−0.27	6.00/−0.52	ns
		XC7K480T	3.37/−0.27	3.48/−0.27	3.76/−0.27	6.00/−0.52	ns

Notes:

- Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage.
- IFF = Input Flip-Flop or Latch
- A Zero "0" Hold Time listing indicates no hold time or a negative hold time.

Table 46: Clock-Capable Clock Input Setup and Hold With MMCM

Symbol	Description	Device	Speed Grade				Units
			1.0V			0.9V	
			-3	-2/-2L	-1	-2L	
Input Setup and Hold Time Relative to Global Clock Input Signal for SSTL15 Standard. ⁽¹⁾							
T _{PSMMCMCC} / T _{PHMMCMCC}	No Delay clock-capable clock input and IFF ⁽²⁾ with MMCM	XC7K70T	2.39/−0.22	2.65/−0.22	2.94/−0.22	2.21/−0.44	ns
		XC7K160T	2.49/−0.20	2.77/−0.20	3.07/−0.20	2.38/−0.47	ns
		XC7K325T	2.55/−0.16	2.85/−0.16	3.14/−0.16	2.60/−0.47	ns
		XC7K355T	2.43/−0.16	2.73/−0.16	3.00/−0.16	2.47/−0.43	ns
		XC7K410T	2.55/−0.16	2.84/−0.16	3.14/−0.16	2.58/−0.47	ns
		XC7K420T	2.47/−0.09	2.73/−0.09	3.02/−0.09	2.40/−0.41	ns
		XC7K480T	2.47/−0.09	2.73/−0.09	3.02/−0.09	2.40/−0.41	ns

Notes:

- Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage.
- IFF = Input Flip-Flop or Latch
- Use IBIS to determine any duty-cycle distortion incurred using various standards.

GTX Transceiver Specifications

GTX Transceiver DC Input and Output Levels

Table 51 summarizes the DC output specifications of the GTX transceivers in Kintex-7 FPGAs. Consult [UG476: 7 Series FPGAs GTX/GTH Transceiver User Guide](#) for further details.

Table 51: GTX Transceiver DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV_{PPOUT}	Differential peak-to-peak output voltage ⁽¹⁾	Transmitter output swing is set to maximum setting	–	–	1000	mV
$V_{CMOUTDC}$	DC common mode output voltage.	Equation based	$V_{MGTAVTT} - DV_{PPOUT}/4$			mV
R_{OUT}	Differential output resistance		–	100	–	Ω
T_{OSKEW}	Transmitter output pair (TXP and TXN) intra-pair skew		–	2	12	ps
DV_{PPIN}	Differential peak-to-peak input voltage (external AC coupled)	>10.3125 Gb/s	150	–	1250	mV
		6.6 Gb/s to 10.3125 Gb/s	150	–	1250	mV
		≤ 6.6 Gb/s	150	–	2000	mV
V_{IN}	Absolute input voltage	DC coupled $V_{MGTAVTT} = 1.2V$	–200	–	$V_{MGTAVTT}$	mV
V_{CMIN}	Common mode input voltage	DC coupled $V_{MGTAVTT} = 1.2V$	–	$2/3 V_{MGTAVTT}$	–	mV
R_{IN}	Differential input resistance		–	100	–	Ω
C_{EXT}	Recommended external AC coupling capacitor ⁽²⁾		–	100	–	nF

Notes:

- The output swing and preemphasis levels are programmable using the attributes discussed in [UG476: 7 Series FPGAs GTX/GTH Transceiver User Guide](#) and can result in values lower than reported in this table.
- Other values can be used as appropriate to conform to specific protocols and standards.

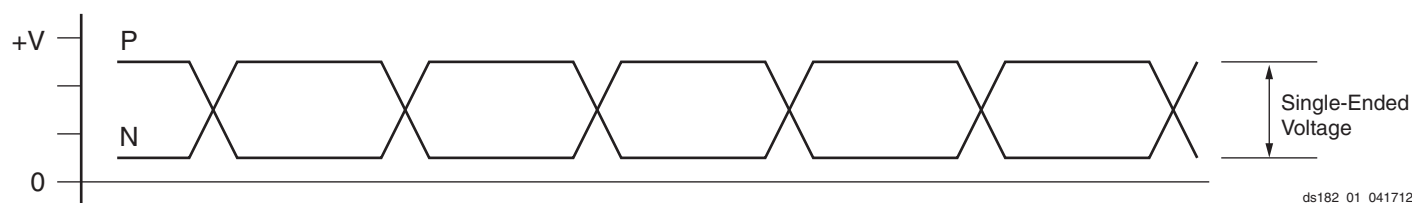


Figure 1: Single-Ended Peak-to-Peak Voltage

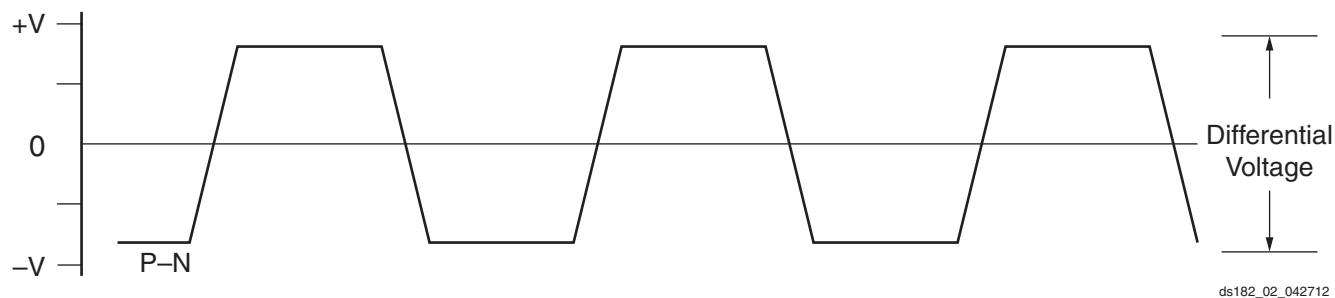


Figure 2: Differential Peak-to-Peak Voltage

Table 56: GTX Transceiver PLL /Lock Time Adaptation

Symbol	Description	Conditions	All Speed Grades			Units
			Min	Typ	Max	
T _{LOCK}	Initial PLL lock		–	–	1	ms
T _{DLOCK}	Clock recovery phase acquisition and adaptation time for decision feedback equalizer (DFE).	After the PLL is locked to the reference clock, this is the time it takes to lock the clock data recovery (CDR) to the data present at the input.	–	50,000	37 x10 ⁶	UI
	Clock recovery phase acquisition and adaptation time for low-power mode (LPM) when the DFE is disabled.		–	50,000	2.3 x10 ⁶	UI

Table 57: GTX Transceiver User Clock Switching Characteristics⁽¹⁾⁽²⁾

Symbol	Description	Conditions	Speed Grade				Units
			1.0V			0.9V	
			-3 ⁽³⁾	-2/-2L ⁽³⁾	-1 ⁽⁴⁾	-2L ⁽⁵⁾	
F _{TXOUT}	TXOUTCLK maximum frequency		412.54	412.54	312.50	237.53	MHz
F _{RXOUT}	RXOUTCLK maximum frequency		412.54	412.54	312.50	237.53	MHz
F _{TXIN}	TXUSRCLK maximum frequency	16-bit data path	412.54	412.54	312.50	237.53	MHz
		32-bit data path	391.08	322.37	250.00	206.27	MHz
F _{RXIN}	RXUSRCLK maximum frequency	16-bit data path	412.54	412.54	312.50	237.53	MHz
		32-bit data path	391.08	322.37	250.00	206.27	MHz
F _{TXIN2}	TXUSRCLK2 maximum frequency	16-bit data path	412.54	412.54	312.50	237.53	MHz
		32-bit data path	391.08	322.37	250.00	206.27	MHz
		64-bit data path	195.54	161.19	125.00	103.14	MHz
F _{RXIN2}	RXUSRCLK2 maximum frequency	16-bit data path	412.54	412.54	312.50	237.53	MHz
		32-bit data path	391.08	322.37	250.00	206.27	MHz
		64-bit data path	195.54	161.19	125.00	103.14	MHz

Notes:

1. Clocking must be implemented as described in [UG476: 7 Series FPGAs GTX/GTH Transceiver User Guide](#).
2. These frequencies are not supported for all possible transceiver configurations.
3. For speed grades -3, -2, -2L (1.0V), a 16-bit data path can only be used for speeds less than 6.6 Gb/s.
4. For speed grade -1, a 16-bit data path can only be used for speeds less than 5.0 Gb/s.
5. For speed grade -2L (0.9V), a 16-bit data path can only be used for speeds less than 3.8 Gb/s.

Table 58: GTX Transceiver Transmitter Switching Characteristics

Symbol	Description	Condition	Min	Typ	Max	Units
F _{GTXTX}	Serial data rate range		0.500	–	F _{GTXMAX}	Gb/s
T _{RTX}	TX Rise time	20%–80%	–	40	–	ps
T _{FTX}	TX Fall time	80%–20%	–	40	–	ps
T _{LLSKEW}	TX lane-to-lane skew ⁽¹⁾		–	–	500	ps
V _{TXOOBVDPP}	Electrical idle amplitude		–	–	15	mV
T _{TXOOBTRANSITION}	Electrical idle transition time		–	–	140	ns
TJ _{12.5}	Total Jitter ⁽²⁾⁽⁴⁾	12.5 Gb/s	–	–	0.28	UI
DJ _{12.5}	Deterministic Jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI
TJ _{11.18}	Total Jitter ⁽²⁾⁽⁴⁾	11.18 Gb/s	–	–	0.28	UI
DJ _{11.18}	Deterministic Jitter ⁽²⁾⁽⁴⁾		–	–	0.17	UI

Table 59: GTX Transceiver Receiver Switching Characteristics

Symbol	Description		Min	Typ	Max	Units
F _{GTXRX}	Serial data rate	RX oversampler not enabled	0.500	–	F _{GTXMAX}	Gb/s
T _{RXELECIDLE}	Time for RXELECIDLE to respond to loss or restoration of data		–	10	–	ns
RX _{OOBVDPP}	OOB detect threshold peak-to-peak		60	–	150	mV
RX _{SST}	Receiver spread-spectrum tracking ⁽¹⁾	Modulated @ 33 KHz	–5000	–	0	ppm
RX _{RL}	Run length (CID)		–	–	512	UI
RX _{PPMTOL}	Data/REFCLK PPM offset tolerance	Bit rates ≤ 6.6 Gb/s	–1250	–	1250	ppm
		Bit rates > 6.6 Gb/s and ≤ 8.0 Gb/s	–700	–	700	ppm
		Bit rates > 8.0 Gb/s	–200	–	200	ppm
SJ Jitter Tolerance ⁽²⁾						
JT_SJ _{12.5}	Sinusoidal Jitter (QPLL) ⁽³⁾	12.5 Gb/s	0.3	–	–	UI
JT_SJ _{11.18}	Sinusoidal Jitter (QPLL) ⁽³⁾	11.18 Gb/s	0.3	–	–	UI
JT_SJ _{10.32}	Sinusoidal Jitter (QPLL) ⁽³⁾	10.32 Gb/s	0.3	–	–	UI
JT_SJ _{9.95}	Sinusoidal Jitter (QPLL) ⁽³⁾	9.95 Gb/s	0.3	–	–	UI
JT_SJ _{9.8}	Sinusoidal Jitter (QPLL) ⁽³⁾	9.8 Gb/s	0.3	–	–	UI
JT_SJ _{8.0}	Sinusoidal Jitter (QPLL) ⁽³⁾	8.0 Gb/s	0.44	–	–	UI
JT_SJ _{6.6_QPLL}	Sinusoidal Jitter (QPLL) ⁽³⁾	6.6 Gb/s	0.48	–	–	UI
JT_SJ _{6.6_CPLL}	Sinusoidal Jitter (CPLL) ⁽³⁾	6.6 Gb/s	0.44	–	–	UI
JT_SJ _{5.0}	Sinusoidal Jitter (CPLL) ⁽³⁾	5.0 Gb/s	0.44	–	–	UI
JT_SJ _{4.25}	Sinusoidal Jitter (CPLL) ⁽³⁾	4.25 Gb/s	0.44	–	–	UI
JT_SJ _{3.75}	Sinusoidal Jitter (CPLL) ⁽³⁾	3.75 Gb/s	0.44	–	–	UI
JT_SJ _{3.2}	Sinusoidal Jitter (CPLL) ⁽³⁾	3.2 Gb/s ⁽⁴⁾	0.45	–	–	UI
JT_SJ _{3.2L}	Sinusoidal Jitter (CPLL) ⁽³⁾	3.2 Gb/s ⁽⁵⁾	0.45	–	–	UI
JT_SJ _{2.5}	Sinusoidal Jitter (CPLL) ⁽³⁾	2.5 Gb/s ⁽⁶⁾	0.5	–	–	UI
JT_SJ _{1.25}	Sinusoidal Jitter (CPLL) ⁽³⁾	1.25 Gb/s ⁽⁷⁾	0.5	–	–	UI
JT_SJ ₅₀₀	Sinusoidal Jitter (CPLL) ⁽³⁾	500 Mb/s	0.4	–	–	UI
SJ Jitter Tolerance with Stressed Eye ⁽²⁾						
JT_TJSE _{3.2}	Total Jitter with Stressed Eye ⁽⁸⁾	3.2 Gb/s	0.70	–	–	UI
JT_TJSE _{6.6}		6.6 Gb/s	0.70	–	–	UI
JT_SJSE _{3.2}	Sinusoidal Jitter with Stressed Eye ⁽⁸⁾	3.2 Gb/s	0.1	–	–	UI
JT_SJSE _{6.6}		6.6 Gb/s	0.1	–	–	UI

Notes:

- Using RXOUT_DIV = 1, 2, and 4.
- All jitter values are based on a bit error ratio of $1e^{-12}$.
- The frequency of the injected sinusoidal jitter is 10 MHz.
- CPLL frequency at 3.2 GHz and RXOUT_DIV = 2.
- CPLL frequency at 1.6 GHz and RXOUT_DIV = 1.
- CPLL frequency at 2.5 GHz and RXOUT_DIV = 2.
- CPLL frequency at 2.5 GHz and RXOUT_DIV = 4.
- Composite jitter with RX and LPM or DFE mode.

Table 65: CPRI Protocol Characteristics

Description	Line Rate (Mb/s)	Min	Max	Units
CPRI Transmitter Jitter Generation				
Total transmitter jitter	614.4	–	0.35	UI
	1228.8	–	0.35	UI
	2457.6	–	0.35	UI
	3072.0	–	0.35	UI
	4915.2	–	0.3	UI
	6144.0	–	0.3	UI
	9830.4	–	Note 1	UI
CPRI Receiver Frequency Jitter Tolerance				
Total receiver jitter tolerance	614.4	0.65	–	UI
	1228.8	0.65	–	UI
	2457.6	0.65	–	UI
	3072.0	0.65	–	UI
	4915.2	0.95	–	UI
	6144.0	0.95	–	UI
	9830.4	Note 1	–	UI

Notes:

1. Tested per SFP+ specification, see Table 64.

Integrated Interface Block for PCI Express Designs Switching Characteristics

More information and documentation on solutions for PCI Express designs can be found at:

<http://www.xilinx.com/technology/protocols/pciexpress.htm>

Table 66: Maximum Performance for PCI Express Designs

Symbol	Description	Speed Grade				Units
		1.0V			0.9V	
		-3	-2/-2L	-1	-2L	
F _{PIPECLK}	Pipe clock maximum frequency	250.00	250.00	250.00	250.00	MHz
F _{USERCLK}	User clock maximum frequency	500.00	500.00	250.00	250.00	MHz
F _{USERCLK2}	User clock 2 maximum frequency	250.00	250.00	250.00	250.00	MHz
F _{DRPCLK}	DRP clock maximum frequency	250.00	250.00	250.00	250.00	MHz

XADC Specifications

Table 67: XADC Specifications

Parameter	Symbol	Comments/Conditions	Min	Typ	Max	Units
V _{CCADC} = 1.8V ± 5%, V _{REFP} = 1.25V, V _{REFN} = 0V, ADCCLK = 26 MHz, T _j = −40°C to 100°C, Typical values at T _j =+40°C						
ADC Accuracy ⁽¹⁾						
Resolution			12	–	–	Bits
Integral Nonlinearity ⁽²⁾	INL		–	–	±3	LSBs
Differential Nonlinearity	DNL	No missing codes, guaranteed monotonic	–	–	±1	LSBs
Offset Error		Offset calibration enabled	–	–	±6	LSBs
Gain Error		Gain calibration disabled	–	–	±0.5	%
Offset Matching		Offset calibration enabled	–	–	4	LSBs
Gain Matching		Gain calibration disabled	–	–	0.3	%
Sample Rate			0.1	–	1	MS/s
Signal to Noise Ratio ⁽²⁾	SNR	F _{SAMPLE} = 500KS/s, F _{IN} = 20KHz	60	–	–	dB
RMS Code Noise		External 1.25V reference	–	–	2	LSBs
		On-chip reference	–	3	–	LSBs
Total Harmonic Distortion ⁽²⁾	THD	F _{SAMPLE} = 500KS/s, F _{IN} = 20KHz	–	70	–	dB
ADC Accuracy at Extended Temperatures (-55°C to 125°C)						
Resolution			10	–	–	Bits
Integral Nonlinearity ⁽²⁾	INL		–	–	±1	LSB (at 10 bits)
Differential Nonlinearity	DNL	No missing codes, guaranteed monotonic	–	–	±1	
Analog Inputs ⁽³⁾						
ADC Input Ranges		Unipolar operation	0	–	1	V
		Bipolar operation	–0.5	–	+0.5	V
		Unipolar common mode range (FS input)	0	–	+0.5	V
		Bipolar common mode range (FS input)	+0.5	–	+0.6	V
Maximum External Channel Input Ranges		Adjacent channels set within these ranges should not corrupt measurements on adjacent channels	–0.1	–	V _{CCADC}	V
Auxiliary Channel Full Resolution Bandwidth	FRBW		250	–	–	KHz
On-Chip Sensors						
Temperature Sensor Error		T _j = –40°C to 100°C.	–	–	±4	°C
		T _j = –55°C to +125°C	–	–	±6	°C
Supply Sensor Error		Measurement range of V _{CCAUX} 1.8V ±5% T _j = –40°C to +100°C	–	–	±1	%
		Measurement range of V _{CCAUX} 1.8V ±5% T _j = –55°C to +125°C	–	–	±2	%
Conversion Rate ⁽⁴⁾						
Conversion Time - Continuous	t _{CONV}	Number of ADCCLK cycles	26	–	32	Cycles
Conversion Time - Event	t _{CONV}	Number of CLK cycles	–	–	21	Cycles
DRP Clock Frequency	DCLK	DRP clock frequency	8	–	250	MHz
ADC Clock Frequency	ADCCLK	Derived from DCLK	1	–	26	MHz
DCLK Duty Cycle			40	–	60	%